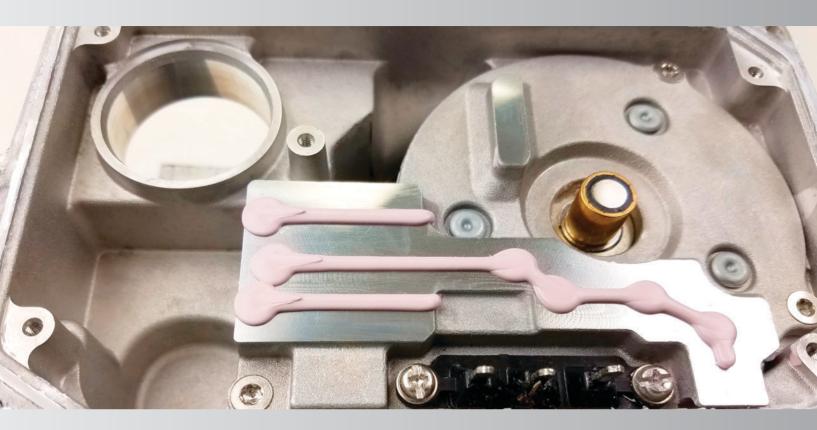
BERGQUIST



BERGQUIST® LIQUI-BOND TLB SA2005RT

TWO-PART, SILICONE THERMAL ADHESIVE

BERGQUIST® *LIQUI-BOND* TLB SA2005RT is a two-part silicone adhesive thermal interface material that delivers high adhesion for a strong structural bond, providing the option to eliminate screws and fasteners while delivering the thermal conductivity of a thermal pad or liquid gap filler. The material's liquid formulation is conducive to automated, high-volume production environments, and its cure adaptability provides excellent process flexibility.

Independent of ambient moisture, *BERGQUIST LIQUI-BOND* TLB SA2005RT reliably cures at multiple temperatures – from room temperature up to 180°C. The cure rate is accelerated at elevated temperatures, achieving maximum shear strength in as fast as 60 seconds.







SHEAR STRENGTH (MPa)	CURE SCHEDULE		
	25°C	50°C	85°C
0.3 (Self-Fixture)	6 hr.	30 min.	5 min.
0.7	1 day	6 hr.	10 min.
1.2	3 days	1 day	1 hr.
1.4	7 days	1 day	1 hr.

PRODUCT PROPERTIES			
Viscosity at 3,000 s ⁻¹ (cP)	70,000		
Thermal Conductivity (W/m•K)	2.0		
Shore A Hardness	65		
Volume Resistivity (Ω•m)	1×10 ¹¹		
Flammability Rating	UL 94 V-0		

Across the Board, Around the Globe. henkel-adhesives.com/thermal Henkel Corporation 14000 Jamboree Road Irvine, CA 92606 United States +1.888.943.6535 Henkel Europe Nijverheidsstraat 7 B-2260, Westerlo Belgium +32.1457.5611 Henkel Asia 332 Meigui South Road WaiGaoQiao FTZ Shanghai 200131 China +86.21.3898.4800

